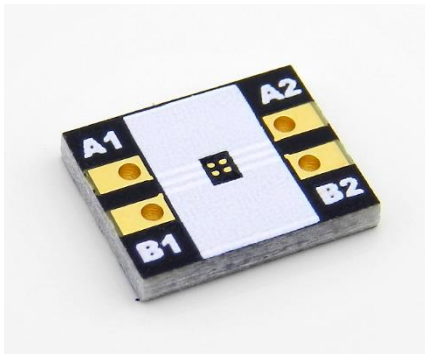


BGA-4 BREAKOUT BOARD

(1.04 x 1.07 mm, 0.5 mm)

SKU: ICB00130

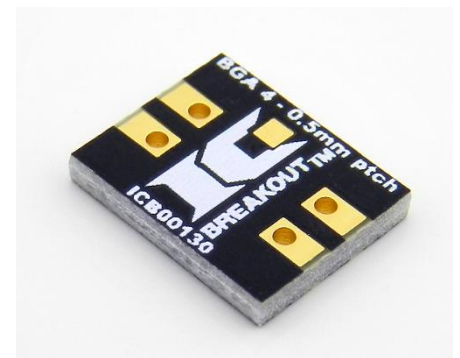


Description

This is a breakout board that was designed to be a DIP adapter for the BGA-4 type SMD packages. This board will require a re-flow oven or hot air gun to solder the part on the board.

Technical Details

Footprint Dimensions	
Body (mm):	1.04 x 1.07
Pitch (mm):	0.5
Thermal Pad (mm):	n/a
Breakout Board Dimensions	
Board Dimensions (mil):	450 x 370
Board Thickness (mil):	62
Through-Hole Spacing (mil):	300 mil (X-axis)
	100 mil (Y-axis)
Breakout Board Specifications	
Board Layers:	2
Finish:	Immersion Gold
Copper:	1 oz
Traces (mil)	10
Trace Lengths (mil):	<200
Pin/Through-Hole Count:	4



What's Included?

Parts Installed on Board:	None
Parts Included (but not installed):	4 PIN Break Away Header (Straight)

Additional Features

- Easily identifiable PIN 1 indicator and PIN numbers
- White silk "Label Pads" allow you to label the pins for quick reference
- Extended through-hole pads make for an easy connection point for surface mount parts
- Breadboard friendly pin spacing
- All boards have been E-tested for failures and are RoHS compliant

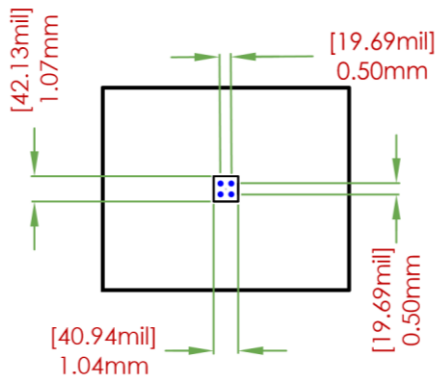
Scale Image



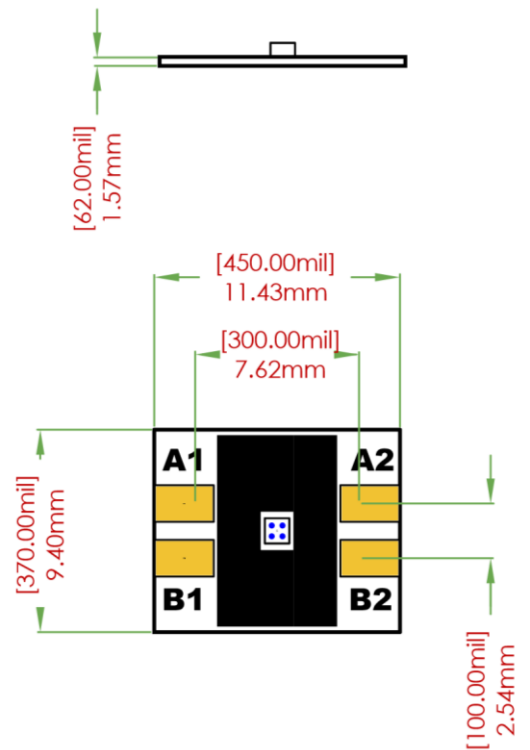
1:1 SCALE

(Print this page to use the scale image to test the fit of the electronic part.)

Dimensions



**FOOTPRINT
DIMENSIONS**



**BREAKOUT BOARD
DIMENSIONS**